



# Mask Aligner MA6

## Karl Suss



### Description

The Karl Suss Mask Aligner performs high resolution photolithography. It offers unsurpassed flexibility in the handling of irregularly shaped substrates of differing thickness, as well as standard size wafers up to 6" in diameter. It uses 5" masks system and it can be operated manually. Enable overlay lithography process with alignment accuracy of +/-2um. The system is also enable backside alignment with accuracy of +/- 3um

Wafers and substrates up to 6 mm thick. The system is equipped with a Hg-Xe vapor lamp. The MA6 has upgraded optics designed to output in the mid-UV range.

### Specifications / Capabilities

Substrate size up to 6" x 6"  
Mask size up to 7" x 7" standard

Exposure Optics:  
Wave length: 365nm  
L-Line and G-Line  
Exposure source at 350 watt

### Link

<http://www.suss.com/en.html>

[http://www.suss.com/fileadmin/user\\_upload/brochures/BR\\_MABA6.pdf](http://www.suss.com/fileadmin/user_upload/brochures/BR_MABA6.pdf)